



**ENVIRONMENTAL AND PACKAGE TESTING DATA FOR SC-89**

<b>Stress</b>	<b>Sample Size</b>	<b>Device Hr./Cyc</b>	<b>Condition</b>	<b>Total Fails</b>	<b>Fail Percentage</b>
85/85	165	25,080	85°C, 85%RH	0	0.00
BOND INT	285	176,250	200°C +N2	0	0.00
HAST	1,255	133,640	130°C, 85%RH	0	0.00
Pressure Pot	2,850	279,280	121°, 15 PSIG	0	0.00
Solder DUNK	715	2,430	260°C, 10SEC	0	0.00
Solderability	392	3,381	883 M2003	0	0.00
Temp Cycle	2,960	1,247,500	-65°C-150°C	0	0.00